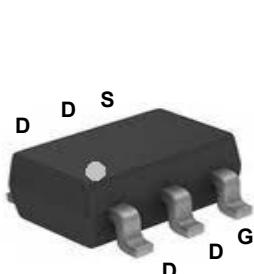
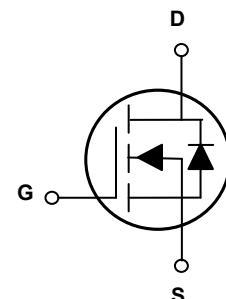


Main Product Characteristics

$V_{(BR)DSS}$	30V
$R_{DS(ON)}$	24mΩ
I_D	6.5A



SOT-23-6L



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for MB/VGA/Vcore and load switch
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The SSF3912 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current – Continuous ($T_C=25^\circ\text{C}$)	I_D	6.5	A
Drain Current – Continuous ($T_C=100^\circ\text{C}$)		4.1	A
Drain Current – Pulsed ¹	I_{DM}	26	A
Single Pulse Avalanche Energy ²	E_{AS}	32	mJ
Single Pulse Avalanche Current ²	I_{AS}	8	A
Power Dissipation ($T_C=25^\circ\text{C}$)	P_D	1.56	W
Power Dissipation – Derate above 25°C	P_D	0.012	W/°C
Storage Temperature Range	T_{STG}	-55 to +150	°C
Operating Junction Temperature Range	T_J	-55 to +150	°C

Thermal Characteristics

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	---	80	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=250\mu\text{A}$	30	---	---	V
BV_{DSS} Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Reference to 25°C , $\text{I}_D=1\text{mA}$	---	0.04	---	$\text{V}/^\circ\text{C}$
Drain-Source Leakage Current	I_{DS}	$\text{V}_{\text{DS}}=30\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$\text{V}_{\text{DS}}=24\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	10	μA
Gate-Source Leakage Current	I_{GSS}	$\text{V}_{\text{GS}}=\pm 20\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA
On Characteristics						
Static Drain-Source On-Resistance ³	$\text{R}_{\text{DS(ON)}}$	$\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=6\text{A}$	---	19	24	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}$, $\text{I}_D=4\text{A}$	---	25	34	$\text{m}\Omega$
Gate Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D=250\mu\text{A}$	1.2	1.6	2.5	V
$\text{V}_{\text{GS(th)}}$ Temperature Coefficient	$\Delta \text{V}_{\text{GS(th)}}$		---	-4	---	$\text{mV}/^\circ\text{C}$
Forward Transconductance	g_{fs}	$\text{V}_{\text{DS}}=10\text{V}$, $\text{I}_D=4\text{A}$	---	6.5	---	S
Dynamic and Switching Characteristics						
Total Gate Charge ^{3, 4}	Q_g	$\text{V}_{\text{DS}}=15\text{V}$, $\text{V}_{\text{GS}}=4.5\text{V}$, $\text{I}_D=6\text{A}$	---	4.1	8	nC
Gate-Source Charge ^{3, 4}	Q_{gs}		---	1	2	
Gate-Drain Charge ^{3, 4}	Q_{gd}		---	2.1	4	
Turn-On Delay Time ^{3, 4}	$\text{T}_{\text{d(on)}}$	$\text{V}_{\text{DD}}=15\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{R}_G=6\Omega$, $\text{I}_D=1\text{A}$	---	2.8	5	nS
Rise Time ^{3, 4}	T_r		---	7.2	14	
Turn-Off Delay Time ^{3, 4}	$\text{T}_{\text{d(off)}}$		---	15.8	30	
Fall Time ^{3, 4}	T_f		---	4.6	9	
Input Capacitance	C_{iss}	$\text{V}_{\text{DS}}=25\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{F}=1\text{MHz}$	---	345	500	pF
Output Capacitance	C_{oss}		---	55	80	
Reverse Transfer Capacitance	C_{rss}		---	32	45	
Gate Resistance	R_g	$\text{V}_{\text{GS}}=0\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$, $\text{F}=1\text{MHz}$	---	3.2	6.4	Ω
Drain-Source Diode Characteristics and Maximum Ratings						
Continuous Source Current	I_s	$\text{V}_G=\text{V}_D=0\text{V}$, Force Current	---	---	6.5	A
Pulsed Source Current ³	I_{SM}		---	---	26	A
Diode Forward Voltage ³	V_{SD}	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V
Reverse Recovery Time	t_{rr}	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_s=1\text{A}$, $\text{di/dt}=100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$	---	---	---	nS
Reverse Recovery Charge	Q_{rr}		---	---	---	nC

Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. $\text{V}_{\text{DD}}=25\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $L=1\text{mH}$, $\text{I}_{\text{AS}}=8\text{A}$, $\text{R}_G=25\Omega$, Starting $T_J=25^\circ\text{C}$.
3. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristics

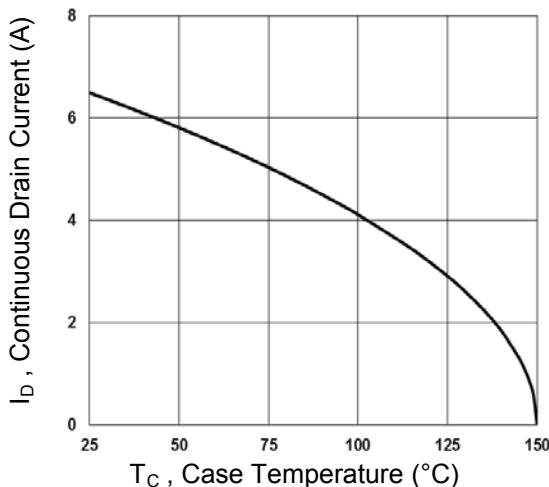


Fig.1 Continuous Drain Current vs. T_c

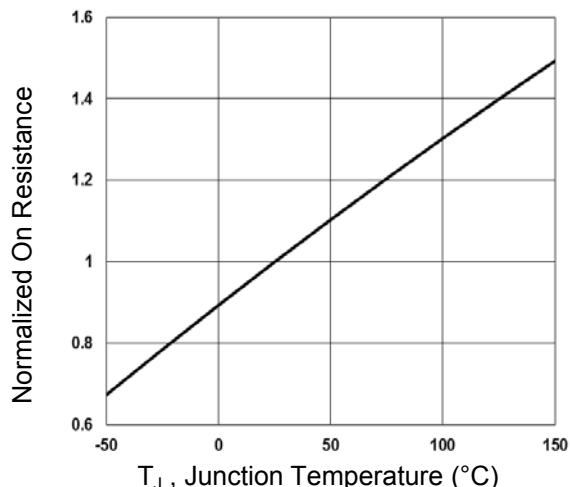


Fig.2 Normalized R_{DS(ON)} vs. T_j

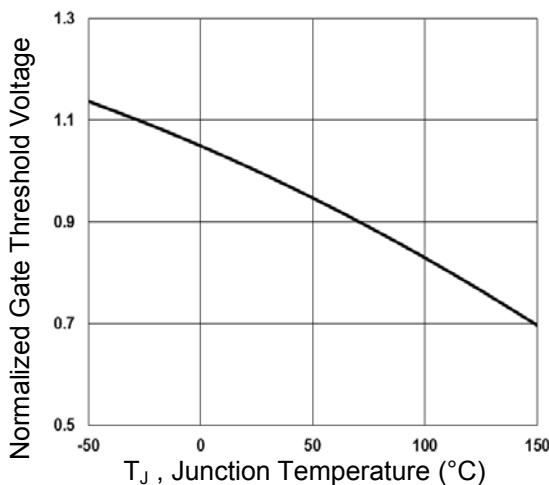


Fig.3 Normalized V_{th} vs. T_j

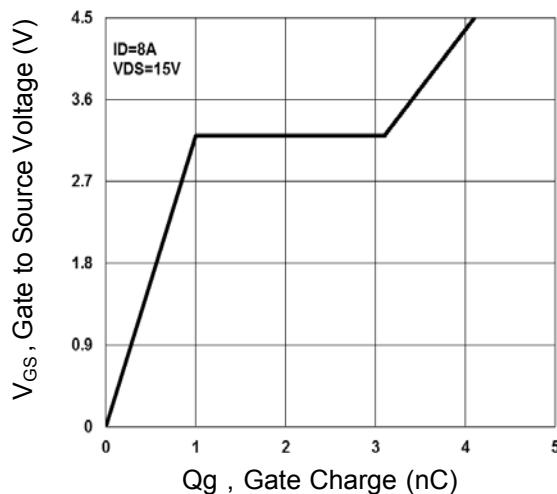


Fig.4 Gate Charge Waveform

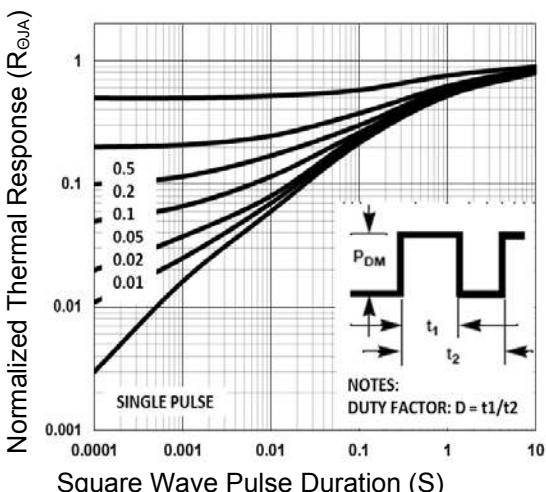


Fig.5 Normalized Transient Response

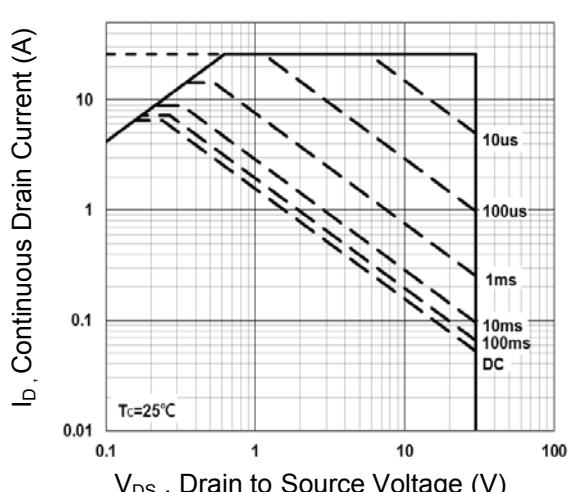


Fig.6 Maximum Safe Operation Area

Typical Electrical and Thermal Characteristics

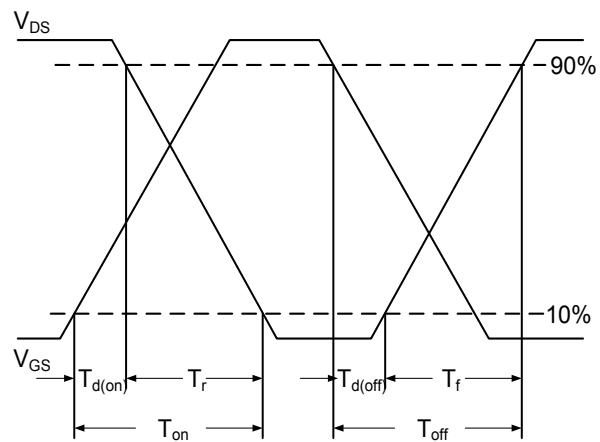


Fig.7 Switching Time Waveform

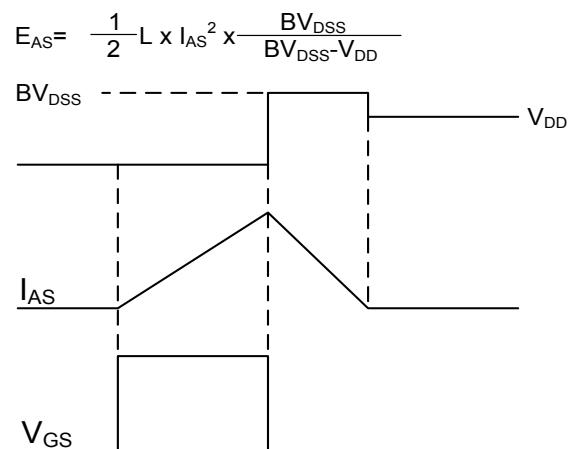
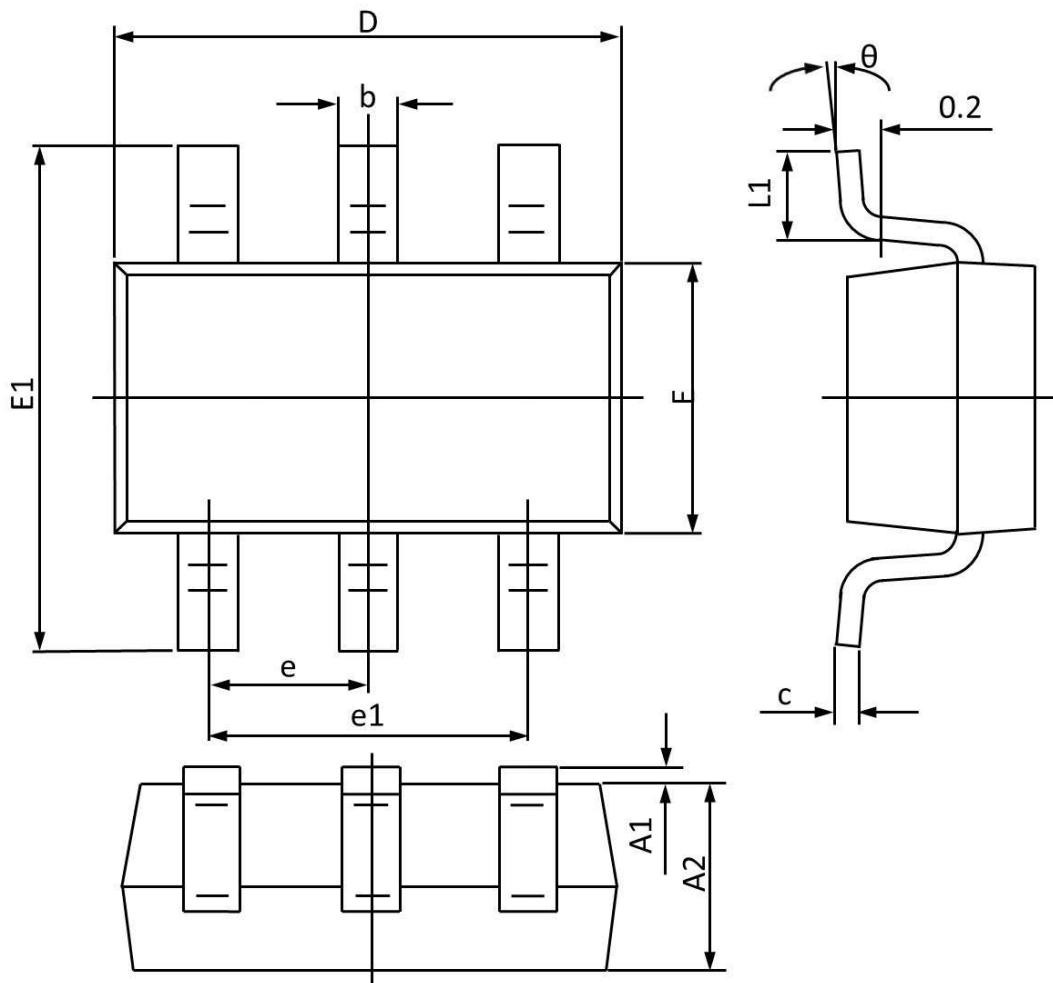


Fig.8 E_{AS} Waveform

Package Outline Dimensions

SOT-23-6L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A1	0.000	0.100	0.000	0.004
A2	1.000	1.200	0.040	0.047
b	0.300	0.500	0.012	0.019
c	0.047	0.207	0.002	0.008
D	2.800	3.000	0.110	0.118
E1	2.600	3.000	0.103	0.118
e	0.950 TYP		0.037 TYP	
e1	1.900 TYP		0.075 TYP	
L1	0.250	0.550	0.010	0.021
θ	0°	8°	0°	8°